

Features

- DC - 3.0 GHz
- 30 Watts
- BeO Ceramic
- Non-Nichrome Resistive Element
- Low VSWR
- 100% Tested

General Specifications

| | |
|---------------------------|-------------------------|
| Resistive Element: | Thick film |
| Substrate: | Beryllium oxide ceramic |
| Terminals: | Thick film silver |

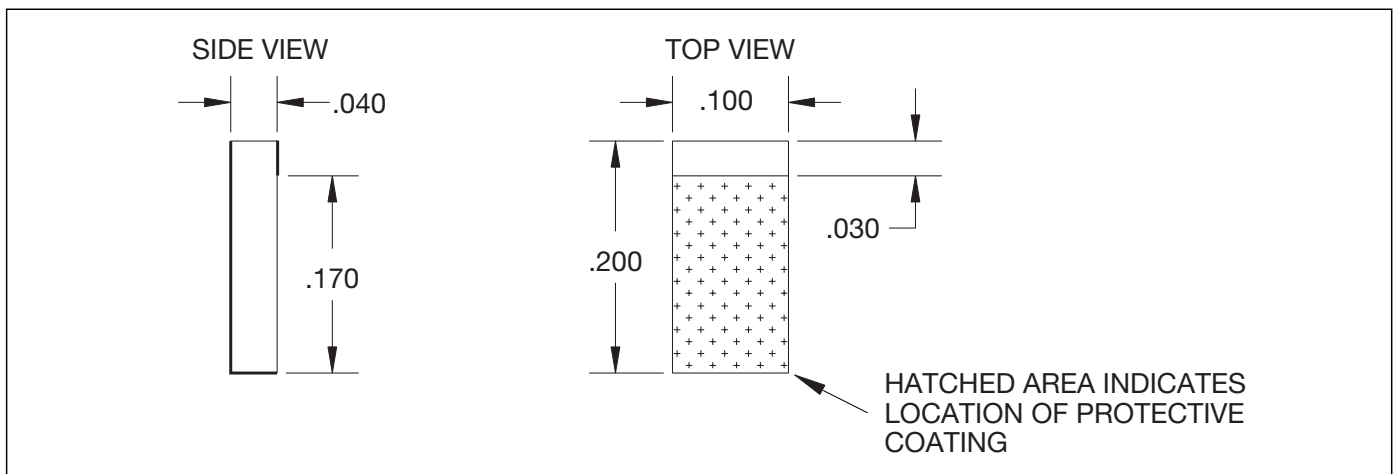
Electrical Specifications

| | |
|--------------------------|--------------------|
| Resistance Value: | 50 ohms, $\pm 2\%$ |
| Frequency Range: | DC - 3.0 GHz |
| Power: | 30 Watts |
| V.S.W.R.: | 1.25:1 |

Notes: Tolerance is $\pm .010$, unless otherwise specified. Operating temperature is -55°C to $+150^{\circ}\text{C}$ (see chart). Designed to meet or exceed applicable portions of MIL-E-5400. All dimensions are in inches.

Specifications subject to change without notice.

Outline Drawing



VER. 12/5/01



Available on Tape and Reel for Pick and Place Manufacturing.

Sales Desk USA: Voice: (800) 544-2414 Fax: (315) 432-9121
Sales Desk Europe: Voice: (+44) 23 92 232392 Fax: (+44) 23 92 251369

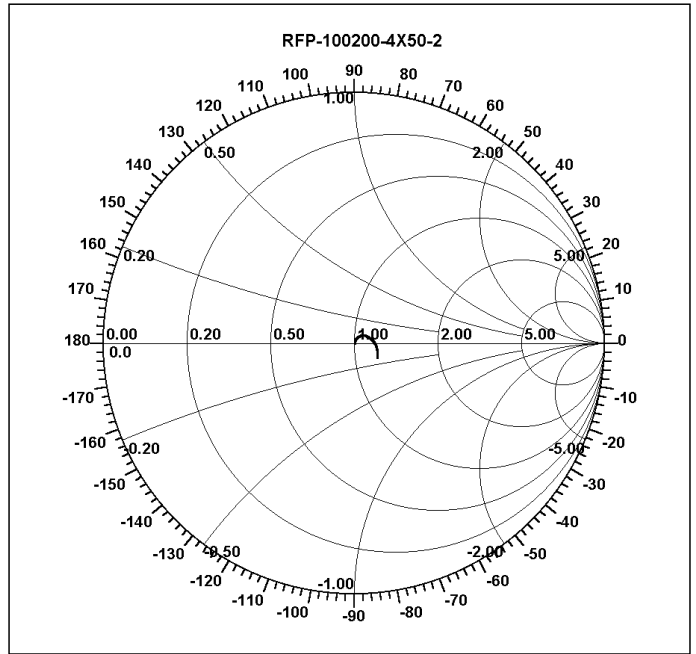
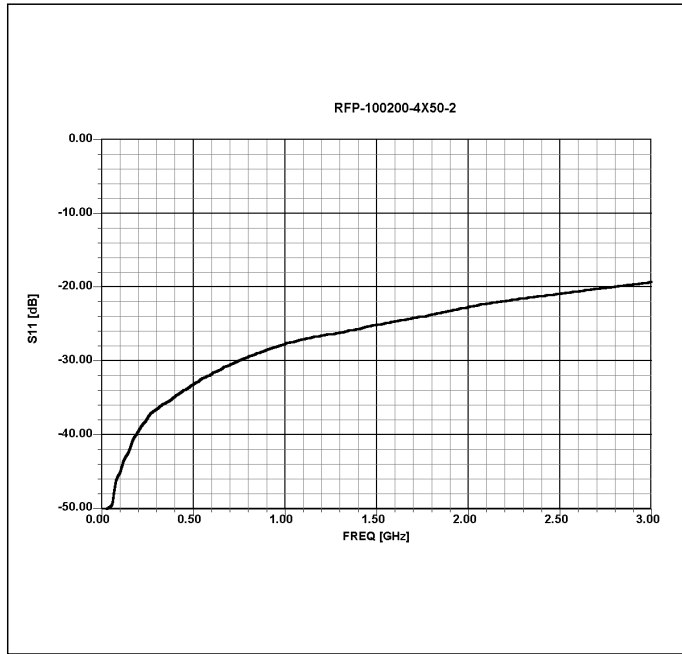
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What'll we think of next?™

Model RFP-100200-4X50-2

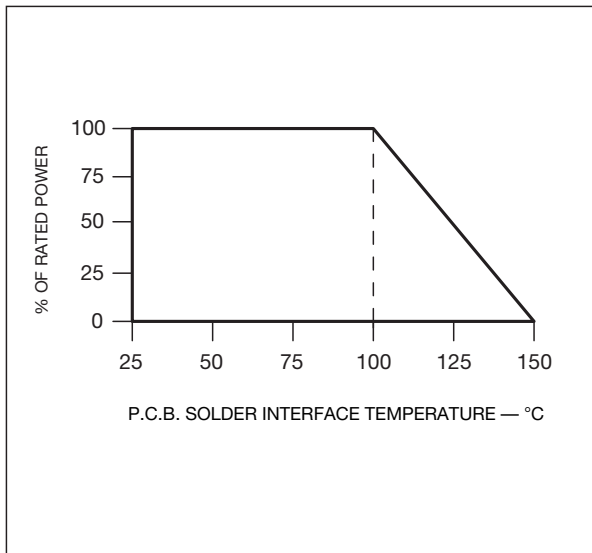


RF Power

Typical Performance



Power Derating



Suggested Mounting Procedures

BOARD LOWER THAN LEAD. BOARD EVEN WITH LEAD.

SUGGESTED STRESS RELIEF METHODS

SCALE: ~

BOARD LOWER THAN LEAD. BOARD HIGHER THAN LEAD.

NOT RECOMMENDED APPLICATION

SCALE: ~

1. Make sure that the devices are mounted on flat surfaces (.001" under the device) to optimize the heat transfer.
2. Position device on mounting surface and solder in place using an indalloy type or a 60/40 type solder.
3. Solder leads in place using a 60/40 type solder with a controlled temperature iron (700°F).

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